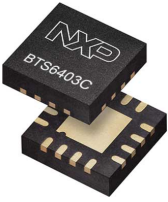


# UM11927

## BTS6403C Evaluation Board Quick Start Guide

Rev. 1.1 — 15 April 2024

User manual



## 1 Introduction

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This document describes the use, design, and test results of the BTS6403C.

### 1.1 BTS6403C product description

The BTS6403C is a wideband, high linearity, pre-driver amplifier for 5G massive MIMO infrastructure applications, with fast on-off switching to support TDD systems. The BTS6403C is designed to operate from 4.4 GHz to 5 GHz.

The BTS6403C is housed in a 3 mm x 3 mm x 0.85 mm 16-terminal HVQFN package.

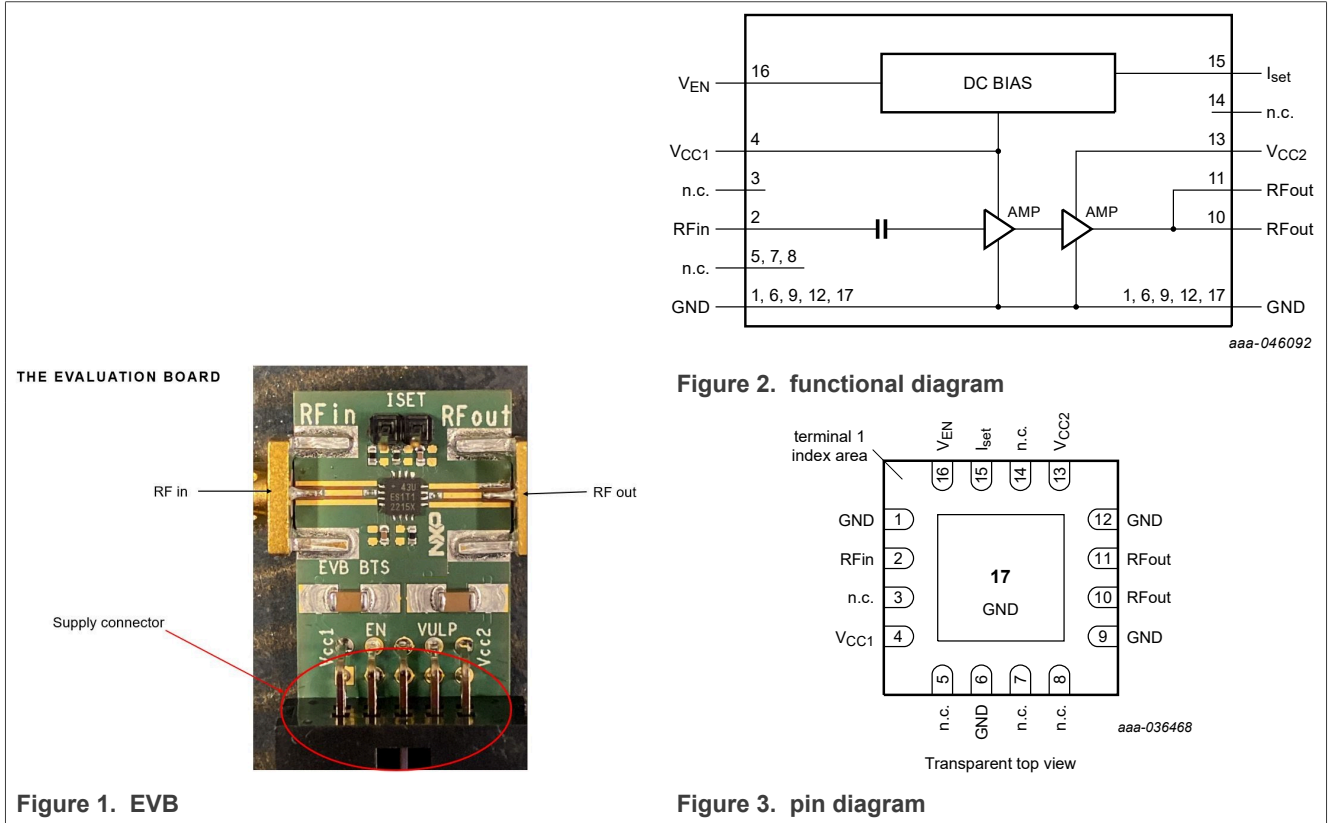
The amplifier is ESD protected on all terminals.

#### **BTS6403C key features and benefits**

- High saturated output power  $P_{o(sat)} = 28$  dBm
- High power-gain  $G_p = 35.5$  dB
- High linearity performance ACLR = -42 dBc
- Unconditionally stable
- Fast switching to support TDD systems
- 5 V single supply, quiescent current 100 mA
- Small 16-terminal leadless package 3 mm x 3 mm x 0.85 mm
- ESD protection on all terminals
- Moisture sensitivity level 1



1.1 BTS6403C product description...continued



## 2 BTS6403C EVB properties

### 2.1 Schematic

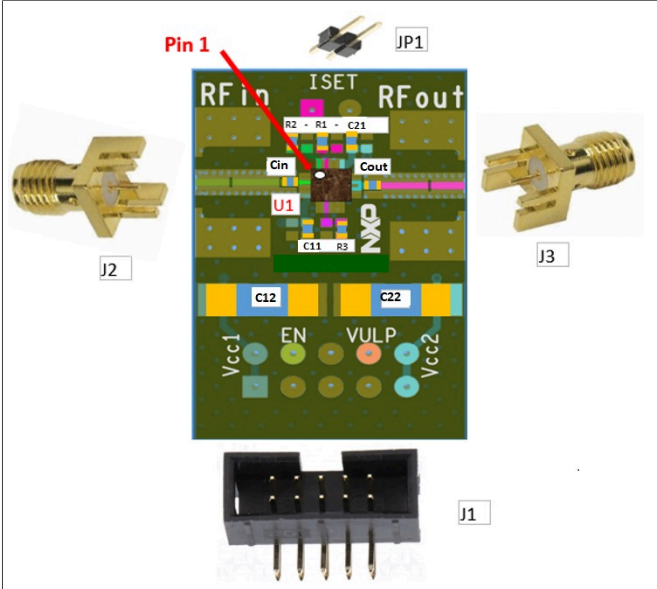


Figure 4. Location of the components

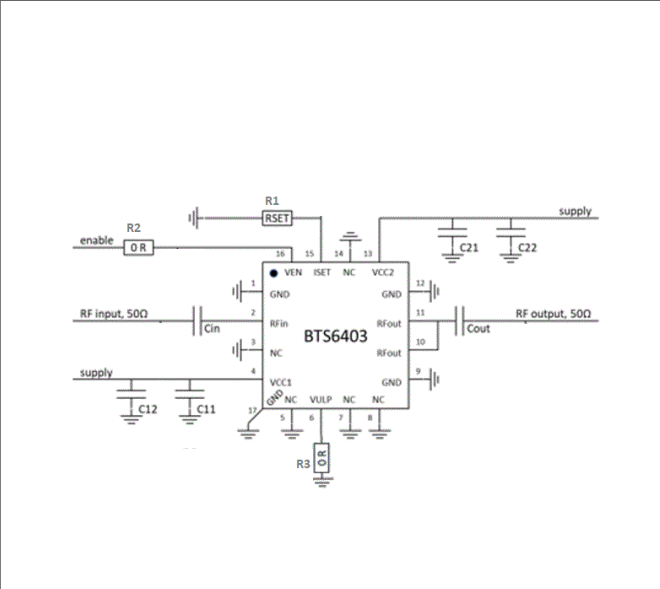


Figure 5. EVB schematic

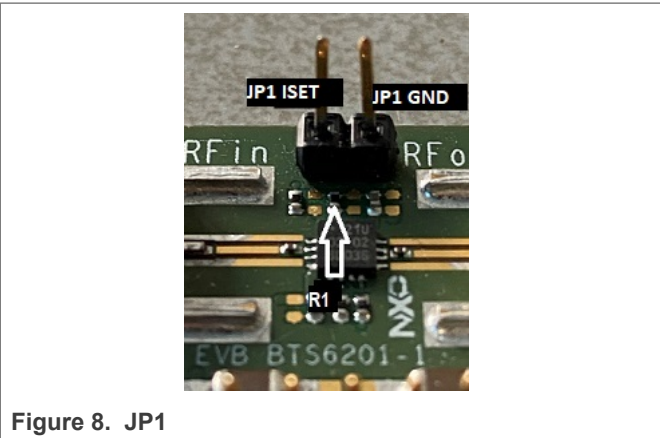
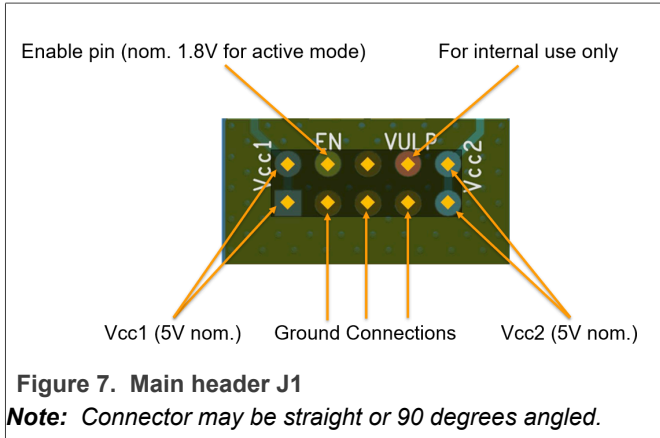
Resistors, Coils, Capacitors						
ID	Shape	Value	Type	Manufacturer	Manufacturer Partnumber	Supplier/type
Cin	C0201	18 pF Tol:	COG	25V	GRM0335C1E180JD01D	MURATA
Cout	C0201	3.9 pF Tol:	COG	25V	GRM0335C1E3R9BD01D	MURATA
C21	C0402	10 nF Tol:	X7R	25V	GCM155R71E103KA37D	▼ RNELL
C11	C0402	10 nF Tol:	X7R	25V	GCM155R71E103KA37D	FARNELL
C12	C1206	10 uF Tol:	X7R	10V	GRM31CR71A106KA01L	MURATA
C22	C1206	10 uF Tol:	X7R	10V	GRM31CR71A106KA01L	MURATA
R1	R0402	10 K Tol:	0	50V	WCR0402-10KFA	YAGEO
R2	R0402	0 R Tol:	0	0	RC0402JR-070RL	FARNELL
R3	R0402	0 R Tol:	0	0	RC0402JR-070RL	FARNELL
-	-	-	-	-	-	-
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-	-	-	-	-	-	-
-	-	-	-	-	-	-
-	-	-	-	-	-	-
ID	Value	Manufacturer	Manufacturer Partnumber	Supplier/type		
JP1		0	PIN HEADER Vertical - single row 3 2,5mm pitch	Texim-Europe		
J2		JOHNSON EMERSON	CONNECTOR SMA CONN JACK END LAUNCH PC GOLD SMA-1,2mm	DIGI-KEY		
J3		JOHNSON EMERSON	CONNECTOR SMA CONN JACK END LAUNCH PC GOLD SMA-1,2mm	DIGI-KEY		
J1		Amphenol Socapex T821	PIN HEADER 10 Way, 2 Row, Right Angle, through hole	RS-online		
EVB		0	PCB BTS6201X Tiger Shakti EVB (BTS6303)	Cibel		

Figure 6. Bill of materials

### 2.2 DC and control connections

Figure 7 shows the DC and enable connection, at the main header (J1). The connector can be straight or 90 degrees. The text is also on the EVB. Figure 8 shows connections JP1 GND, and JP1 ISET. JP1 (ISET) on the EVB can be applied to adjust the quiescent current in the final stage of the amplifier. R1 should be removed in case JP1 is applied to adjust the bias current.

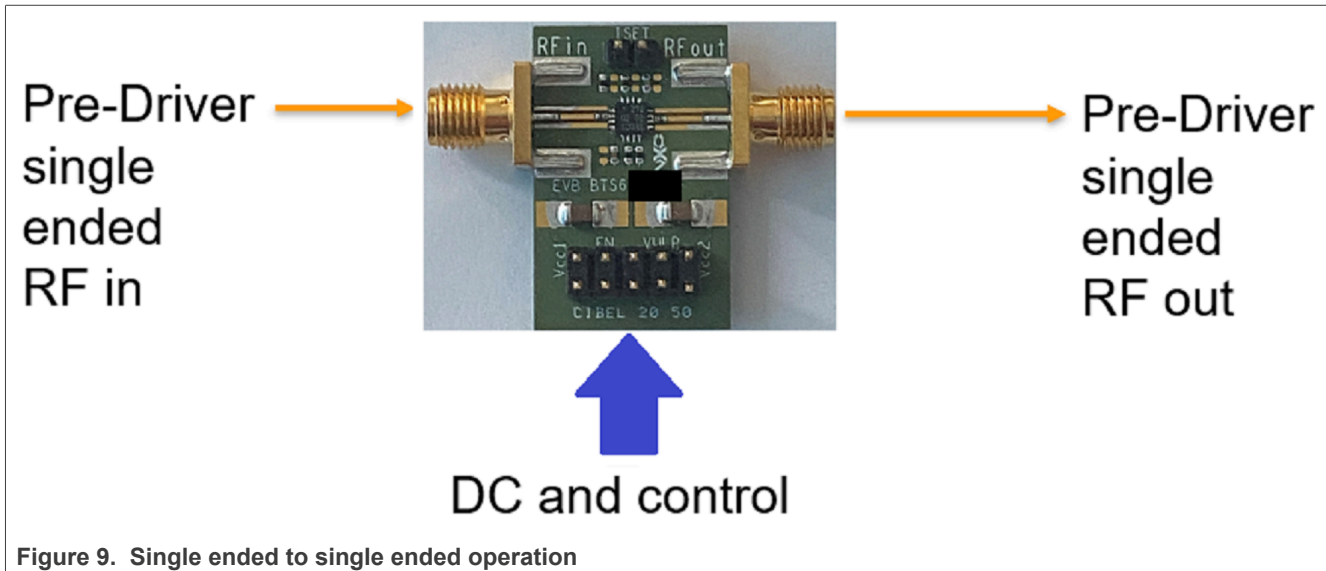
**Note:** NXP recommends that, using the setup as is shown in Figure 8 is R1 (10 kΩ).



### 2.3 Operations

Figure 9 shows the connections in a single ended to single ended operation.

If differential to single ended operation is also needed, NXP refers to UM11918 of the BTS6305U.



### 3 Measurements results

In the below graphics, the Spar measurements are shown. Measured at nominal conditions  $V_{CC} = 5\text{ V}$ ,  $T_{\text{case}} = 25\text{ }^{\circ}\text{C}$ ,  $R_{\text{set}} = 10\text{ k}\Omega$ .

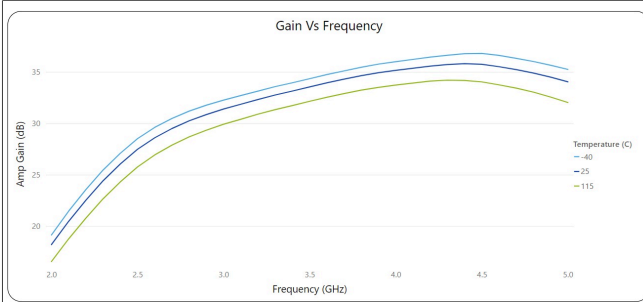


Figure 10. Gain at nominal conditions

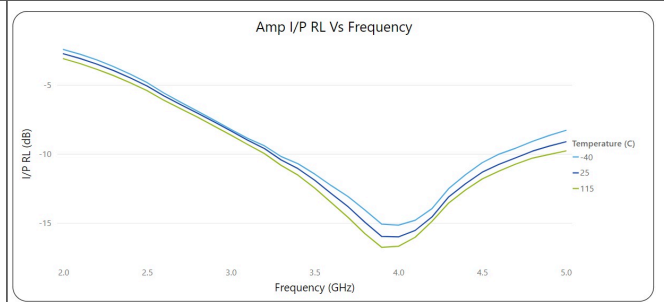


Figure 11.  $RL_i$  at nominal conditions

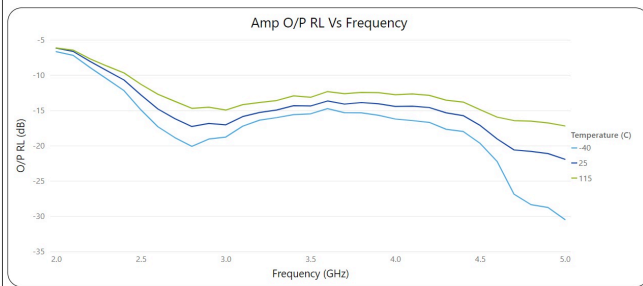


Figure 12.  $RL_o$  at nominal conditions

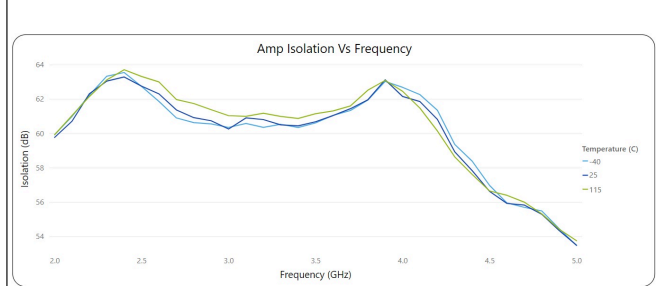


Figure 13.  $ISL_r$  (Gain mode) at nominal conditions

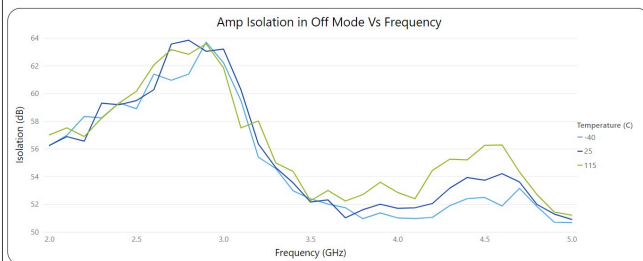


Figure 14.  $ISL_r$  (off mode) at nominal conditions

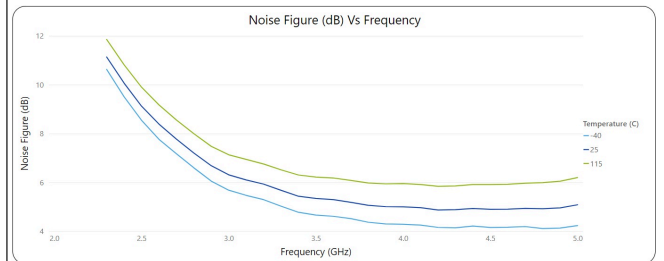


Figure 15. NF at nominal conditions

## 4 Abbreviations

Table 1. Abbreviations

Acronym	Description
ACLR	adjacent channel leakage ratio
ESD	electrostatic discharge
EVB	evaluation board
MIMO	massive multiple-input multiple-output
RF	radio frequency
TDD	time-division duplexing

## 5 EMC information

**CAUTION**

This product has not undergone formal EMC assessment. It is the responsibility of the user to ensure that any finished assembly complies with applicable regulations on EMC interference. EMC testing, and other testing requirements for CE is the responsibility of the user.

## 6 Revision history

Table 2. Revision history

Document ID	Release date	Description
UM11927 Rev. 1.1	15 April 2024	<ul style="list-style-type: none"><li>Updated Legal information and brought to current standard</li></ul>
UM11927 Rev. 1	23 May 2023	<ul style="list-style-type: none"><li>Initial release of user manual</li></ul>

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